

HiPerFRED

 V_{RRM} 1200 V

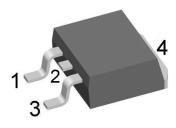
8 A

40 ns

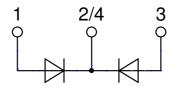
High Performance Fast Recovery Diode Low Loss and Soft Recovery Common Cathode

Part number

DSEC16-12AS



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-263 (D2Pak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments; the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

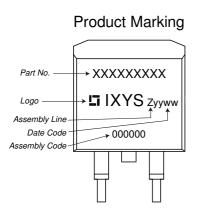
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Fast Dio	de			1	Ratings	S	
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking v	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			60	μΑ
		$V_R = 1200 \text{ V}$	$T_{VJ} = 150$ °C			0.25	mA
V _F	forward voltage drop	I _F = 10 A	$T_{VJ} = 25^{\circ}C$			2.94	V
		$I_F = 20 A$				3.57	V
		I _F = 10 A	T _{vJ} = 150°C			1.96	V
		$I_F = 20 A$				2.56	V
I FAV	average forward current	T _C = 135°C	T _{vJ} = 175°C			8	Α
		rectangular $d = 0.5$					
V _{F0}	threshold voltage	and addition only	$T_{VJ} = 175$ °C			1.20	٧
r _F	slope resistance	ess calculation only				57	mΩ
R _{thJC}	thermal resistance junction to cas	е				2.5	K/W
thCH	thermal resistance case to heatsing	nk			0.25		K/W
P _{tot}	total power dissipation		$T_{\text{C}} = 25^{\circ}\text{C}$			60	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			40	Α
C¹	junction capacitance	$V_R = 600 \text{V} f = 1 \text{MHz}$	$T_{VJ} = 25^{\circ}C$		3		pF
I _{RM}	max. reverse recovery current	<u>, </u>	$T_{VJ} = 25 ^{\circ}\text{C}$		4		Α
		$I_F = 10 \text{ A}; V = 800 \text{ V}$	$T_{VJ} = 125$ °C		8		Α
t _{rr}	reverse recovery time	$\begin{cases} I_F = 10 \text{ A; V} = 800 \text{ V} \\ -d_F/dt = 200 \text{ A/}\mu\text{s} \end{cases}$	$T_{VJ} = 25 ^{\circ}C$		40		ns
	•)	$T_{VJ} = 125$ °C		115		ns



Package TO-263 (D2Pak)				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I _{RMS}	RMS current	per terminal			35	Α	
T _{VJ}	virtual junction temperature		-55	i	175	°C	
T _{op}	operation temperature		-55		150	°C	
T _{stg}	storage temperature		-55	i	150	°C	
Weight				2		g	
F _c	mounting force with clip		20	1	60	N	



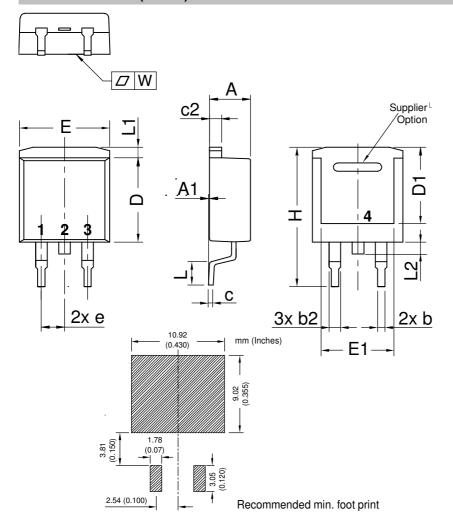
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEC16-12AS	DSEC16-12AS	Tape & Reel	800	507922
Alternative	DSEC16-12AS-TUB	DSEC16-12AS	Tube	50	507915

Similar Part	Package	Voltage class
DSEC16-12A	TO-220AB (3)	1200

Equivalent Circuits for Simulation			* on die level	T _{vJ} = 175 °C
$I \rightarrow V_0$	R_0	Fast Diode		
V _{0 max}	threshold voltage	1.2		V
R _{0 max}	slope resistance *	54		$m\Omega$

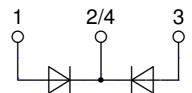


Outlines TO-263 (D2Pak)



Dim.	Millir	neter	Inches		
.וווו	min	max	min	max	
Α	4.06	4.83	0.160	0.190	
A1	typ.	0.10	typ. 0.004		
A2	2.	41	0.095		
b	0.51	0.99	0.020	0.039	
b2	1.14	1.40	0.045	0.055	
С	0.40	0.74	0.016	0.029	
c2	1.14	1.40	0.045	0.055	
D	8.38	9.40	0.330	0.370	
D1	8.00	8.89	0.315	0.350	
D2	2	.5	0.098		
Е	9.65	10.41	0.380	0.410	
E1	6.22	8.50	0.245	0.335	
е	2,54	BSC	0,100 BSC		
e1	4.5	28	0.1	69	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	1.02	1.68	0.040	0.066	
W	typ. 0.02	0.040	typ. 0.0008	0.002	

All dimensions conform with and/or within JEDEC standard.





Fast Diode

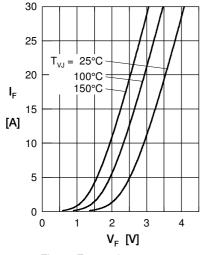


Fig. 1 Forward current I_F versus V_F

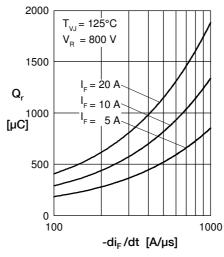


Fig. 2 Typ. reverse recov. charge Q_r versus $-di_F/dt$

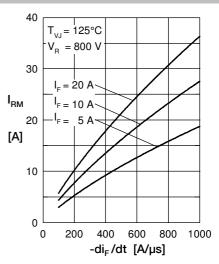


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

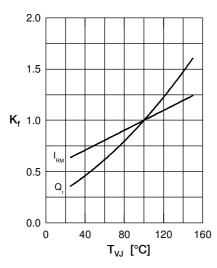
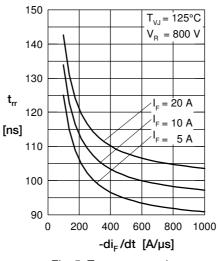


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus T_{VJ}



 $\begin{array}{ccc} \text{Fig. 5} & \text{Typ. recovery time} \\ & t_{\text{rr}} \, \text{versus -} \text{di}_{\text{F}} / \text{dt} \end{array}$

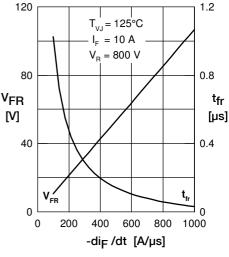


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_{F}/dt

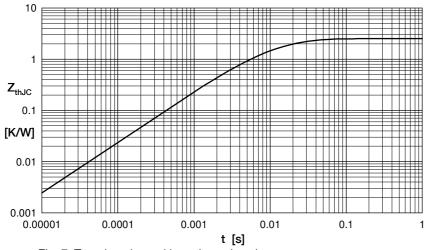


Fig. 7 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t _i (s)
1	1.449	0.0052
2	0.558	0.0003
3	0.493	0.017